

CRS06

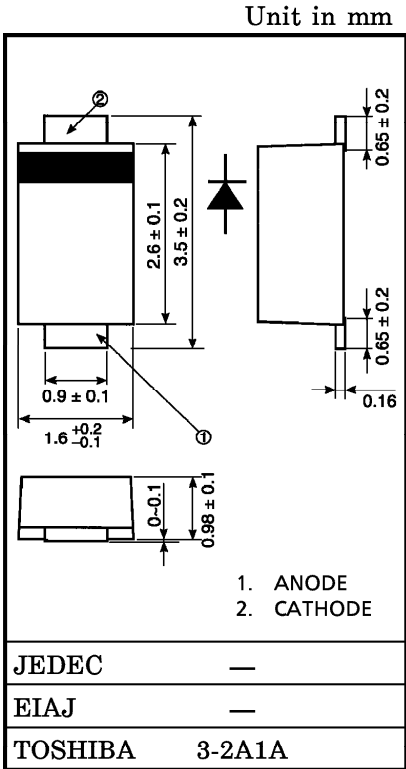
SWITCHING TYPE POWER SUPPLY APPLICATIONS

PORTABLE EQUIPMENT BATTERY APPLICATIONS

- Forward Voltage : $V_{FM} = 0.36 \text{ V (Max.)}$
- Average Forward Current : $I_F (AV) = 1.0 \text{ A}$
- Repetitive Peak Reverse Voltage : $V_{RRM} = 20 \text{ V}$
- Small Package : S-FLAT™ (Toshiba designation)

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	20	V
Average Forward Current	I_O	1.0	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	20 (50 Hz)	A
Junction Temperature	T_j	-40~125	°C
Storage Temperature Range	T_{stg}	-40~125	°C



Weight : 0.013 g

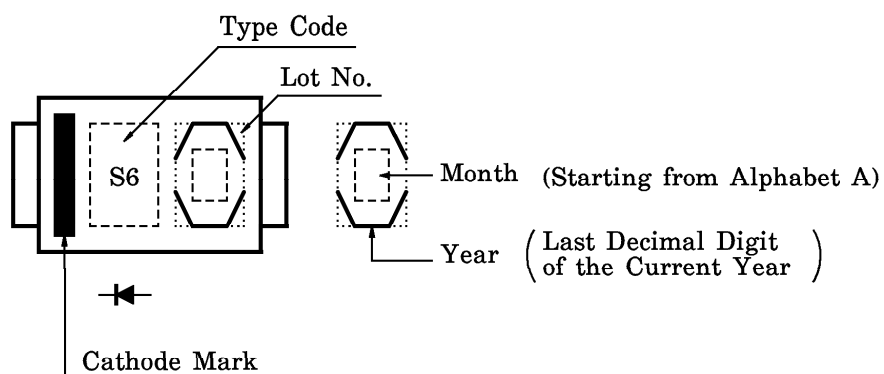
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM} (1)$	$I_{FM} = 0.1 \text{ A}$	—	0.20	—	V
	$V_{FM} (2)$	$I_{FM} = 0.7 \text{ A}$	—	0.30	—	V
	$V_{FM} (3)$	$I_{FM} = 1.0 \text{ A}$	—	0.32	0.36	V
Repetitive Peak Reverse Current	$I_{RRM} (1)$	$V_{RRM} = 5 \text{ V}$	—	0.06	—	mA
	$I_{RRM} (2)$	$V_{RRM} = 20 \text{ V}$	—	—	1.0	mA
Junction Capacitance	C_j	$V_R = 10 \text{ V}, f = 1.0 \text{ MHz}$	—	60	—	pF
Thermal Resistance	$R_{th} (j-a)$	On ceramic substrate (Soldering Land 2 mm × 2 mm)	—	—	70	°C / W
		On glass-epoxy substrate (Soldering Land 2 mm × 2 mm)	—	—	140	°C / W

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MARKING



FOLLOWING INDICATES THE DATE OF MANUFACTURE

0	1	2	3	4
5	6	7	8	9

STANDARD SOLDERING PAD

Unit : mm

